

Product Change Notice (PCN)

Subject: Add Alternate Fabrication Location

Publication Date: 2/27/2026

Effective Date: 9/30/2026

Revision Description:

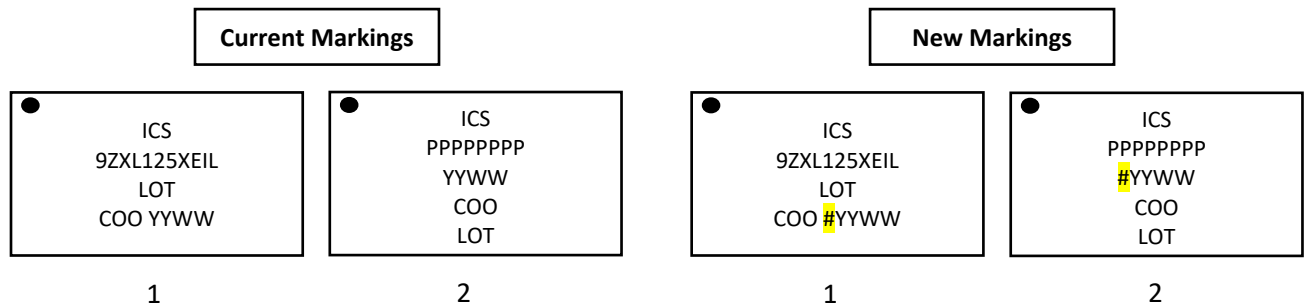
Initial Release

Description of Change:

This notification is to advise our customer that Renesas has qualified Semiconductor Manufacturing International Corporation (SMIC) as an alternative wafer fabrication location for selected products in the affected product list below. There is no change to process technology, product data sheet and the orderable part number.

For information only - device top marking format is also being revised for the 9ZXL parts to include “#” to denote the stepping number, used to differentiate the wafer fabrication location as shown below.

The device marking format change will take place immediately (it is not governed by the effective date of this PCN and PCN effective date will not apply). There will be no change to part number, form, fit, function, reliability, and quality of the products.



1) 9ZXL125xEIL (current marking)

- Line 1: ICS
- Line 2: Part name where X is 1, or 2
- Line 3: LOT= Assembly lot no
- Line 4:
 - COO = Country of Origin
 - YY = last 2 digits of year
 - WW = Workweek

1) 9ZXL125xEIL (new marking)

- Line 1: ICS
- Line 2: Part name where X is 1, or 2
- Line 3: LOT= Assembly lot no
- Line 4:
 - COO = Country of Origin
 - # = Device Step
 - YY = last 2 digits of year
 - WW = Workweek

2) 9ZXL085xEKILF/9ZXL065xEKILF/ ZXL0451EKILF (current marking)

- Line 1: ICS
- Line 2: Part name
- Line 3:
 - YY = last 2 digits of year
 - WW = Workweek
- Line 4: COO = Country of Origin
- Line 5: LOT= Assembly lot no

2) 9ZXL085xEKILF/9ZXL065xEKILF/ ZXL0451EKILF (new marking)

- Line 1: ICS
- Line 2: Part name
- Line 3:
 - # = Device Step
 - YY = last 2 digits of year
 - WW = Workweek
- Line 4: COO = Country of Origin
- Line 5: LOT= Assembly lot no

Affected Product List:

| | | | | |
|------------------|----------------|-----------------|------------------|------------------|
| 9QXL2001CNHGK | 9QXL2001CNHGK8 | 9QXL2001CNHGK/n | 9QXL2001CNHGK8/n | 9QXL2001CNHGK8/W |
| 9QXL2001CNHGK8/S | 9ZXL1251EKILF | 9ZXL1251EKILFT | 9ZXL1252EKILF | 9ZXL1252EKILFT |
| 9ZXL0851EKILF | 9ZXL0851EKILFT | 9ZXL0851EKILF/W | 9ZXL0852EKILF | 9ZXL0852EKILFT |
| 9ZXL0853EKILF | 9ZXL0853EKILFT | 9ZXL0651EKILF | 9ZXL0651EKILFT | 9ZXL0652EKILF |
| 9ZXL0652EKILFT | 9ZXL0451EKILF | 9ZXL0451EKILFT | | |

Reason for Change:

The change is for increased manufacturing capacity and business continuity.

Impact on Fit, Form, Function, Quality & Reliability:

The change has no impact on the Fit, Form, Function, Quality & Reliability of the product. Component level Qualification and Characterization tests verify that product performance falls within the current datasheet spec. Please reach out to sales representative for the char data comparison if necessary.

Product Identification:

Stepping mark on the device top mark can be used to identify the alternate fab location. The following table provides the stepping mark for each of these affected products and alternate fab locations.

| Orderable part number | TSMC Stepping | SMIC Stepping | Orderable part number | TSMC Stepping | SMIC Stepping |
|-----------------------|---------------|---------------|-----------------------|---------------|---------------|
| 9QXL2001CNHGK | ZA | ZC | 9ZXL0851EKILF/W | Z | ZC |
| 9QXL2001CNHGK8 | | | 9ZXL0852EKILF | Z | ZB |
| 9QXL2001CNHGK/n | | | 9ZXL0852EKILFT | Z | ZD |
| 9QXL2001CNHGK8/n | | | 9ZXL0853EKILF | | |
| 9QXL2001CNHGK8/W | | | 9ZXL0853EKILFT | | |
| 9QXL2001CNHGK8/S | | | | | |
| 9ZXL1251EKILF | Z | ZC | 9ZXL0651EKILF | Z | ZB |
| 9ZXL1251EKILFT | | | 9ZXL0651EKILFT | | |
| 9ZXL1252EKILF | ZA | ZD | 9ZXL0652EKILF | Z | ZB |
| 9ZXL1252EKILFT | | | 9ZXL0652EKILFT | | |
| 9ZXL0851EKILF | Z | ZC | 9ZXL0451EKILF | Z | ZB |
| 9ZXL0851EKILFT | | | 9ZXL0451EKILFT | | |

Qualification Status: Completed

Sample Availability Date: 6/30/2026

Device Material Declaration: Available upon request

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 210 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 210 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact idt-pcn@lm.renesas.com

Appendix A - Qualification Results
1) Product : 9QXL2001

Fab Base: AP973S

Process Technology: 0.18MS, 1P5M

Fab Location: SMIC - China

Assembly Location: UTAC - Thailand

| Test Description | Conditions | Sample Size | Results (rej/SS) | Comments |
|---|--|-------------|-------------------------------|-------------------------------|
| High Temperature Operating Life | JESD22-A108, Tj 125 °C, Vccmax, 1000 hrs | 77 | 0/77 | Pass |
| ESD: Human Body Model | JESD22-A114 (JS-001) Classification | 5 | 0/5 | Pass, Class 2 (2000V) |
| ESD: Charged Device Model | JESD22-C101 Classification | 5 | 0/5 | Pass, Class C3 (1000V) |
| Latch-Up | JESD78, +/-100mA | 6 | 0/6 | Pass, T _A at 85 °C |
| Electrical Characterization | Datasheet | 30 | Results reported in Datasheet | Complete |
| Temperature Cycling§ | JESD22-A104, -55 °C to +125 °C, 700 cycles | 80 | 0/80, x3 lots | Pass |
| Highly Accelerated Temperature and Humidity stress (Biased) § | JESD22-A110, +130 °C, 85% R.H., Vccmax, 96 hrs | 80 | 0/80, x3 lots | Pass |
| High Temperature Storage Life | JESD22-A103, +150 °C, 1000 hrs | 80 | 0/80, x3 lots | Pass |
| Bond Pull Strength | M2011 | 5 | 0/5, x 3 lots | Pass |
| Bond Shear | JESD22-B116 | 5 | 0/5, x 3 lots | Pass |
| Solderability Test | J-STD-002 | 5 | 0/5, x 3 lots | Pass |
| Moisture Classification | J-STD-020 | 25 | 0/25, x2 lots | Pass MSL3, 260 °C |

§ With MSL preconditioning per JESD22-A113, MSL 3 (260 °C)

2) Product : 9ZXL1252, 9ZXL0451, 9ZXL0651, 9ZXL0652, 9ZXL0851, 9ZXL0852, 9ZXL0853
9ZXL1251

Fab Base: AP964S

Process Technology: 0.18MS 1P5M

Fab Location: SMIC – China

- Assembly Location: Greatek – Taiwan

| Test Description | Conditions | Sample Size | Results (rej/SS) | Comments |
|--|--|-------------|-----------------------|------------------------------|
| High Temperature Operating Life | JESD22-A108, Tj 125°C, Vccmax, 1000 hrs | 77 | 0/77, x 2 lots | Pass |
| Early Life Failure Rate | JESD22-A108, Tj 125°C, Vccmax, 48 hrs | 1000 | 0/1000, x 3 lots | Pass |
| ESD: Human Body Model | JESD22-A114 (JS-001) Classification | 5 | 0/5 | Pass, Class 2 (2500V) |
| ESD: Charged Device Model | JESD22-C101 Classification | 5 | 0/5 | Pass, Class C2 (1000V) |
| Latch-Up | JESD78, +/-200mA | 6 | 0/6 | Pass, T _A at 25°C |
| Electrical Characterization | Datasheet | 10 | Reported in Datasheet | Completed |
| Temperature Cycling [§] | JESD22-A104, -55°C to +125°C, 840 cycles | 77 | 0/77, x 3 lots | Pass |
| Highly Accelerated Temperature and Humidity stress (Biased) [§] | JESD22-A110, +130°C, 85% R.H., V _{CCmax} , 96 hrs | 77 | 0/77, x 3 lots | Pass |
| High Temperature Storage | JESD22-A103, +150°C, 1000 hrs | 77 | 0/77, x 3 lots | Pass |
| Bond Pull Strength | M2011 | 5 | 0/5, x 3 lots | Pass |
| Bond Shear | JESD22-B116 | 5 | 0/5, x 3 lots | Pass |
| Moisture Classification | J-STD-020, MSL3 / 260°C | 25 | 0/25, x 3 lots | Pass MSL 3 |

- Assembly Location: ASEK - Taiwan

| Test Description | Conditions | Sample Size | Results (rej/SS) | Comments |
|--|--|-------------|-----------------------|-----------|
| High Temperature Operating Life | JESD22-A108, Tj 125°C, Vccmax, 1000 hrs | 77 | 0/77 | Pass |
| Electrical Characterization | Datasheet | 10 | Reported in Datasheet | Completed |
| Temperature Cycling [§] | JESD22-A104, -55°C to +125°C, 840 cycles | 77 | 0/77, x 3 lots | Pass |
| Highly Accelerated Temperature and Humidity stress (Biased) [§] | JESD22-A110, +130°C, 85% R.H., V _{CCmax} , 96 hrs | 77 | 0/77, x 3 lots | Pass |

| | | | | |
|--------------------------|-------------------------------|----|----------------|------------|
| High Temperature Storage | JESD22-A103, +150°C, 1000 hrs | 77 | 0/77, x 3 lots | Pass |
| Bond Pull Strength | M2011 | 5 | 0/5, x 3 lots | Pass |
| Bond Shear | JESD22-B116 | 5 | 0/5, x 3 lots | Pass |
| Moisture Classification | J-STD-020, MSL3 / 260°C | 25 | 0/25, x 3 lots | Pass MSL 3 |

Note:

§ With MSL preconditioning per JESD22-A113, MSL 3 / 260°C